

CALL FOR PAPERS

IEEE Systems, Man, and Cybernetics Magazine

Special Issue on Cooperative design, visualization, engineering, and applications

I. AIM AND SCOPE

From the fast development of the information technology applied to design visualization, engineering and many other fields, we can see a very strong demand in supporting the interactions and cooperation. The field of technological support to the cooperative working within these fields has never been so active. This is due to the high-speed internet, availability of low-cost data storage and the advance of many emerging technologies such as *Artificial Intelligence* · The Industrial Internet of Things (IIoT), Metaverse, Blockchain, Cloud Computing, Cyber Security etc.

This special issue will focus on the technical advance and achievement of the support to the cooperation and interaction, both theoretical and practical.

II. TOPICS

The topics relevant to the special issue include but are not limited to the following:

- Multi-user, multi-location, multi-modal cooperative design including system architecture, user interface, prototyping, design for total life cycle support etc.
- Cooperative visualization for multiple users, multiple locations, multi-modal displays, web applications, textual and multimedia 2D, 3D desktop interfaces, 3D virtual world environments, and multiple user embedded systems etc.
- Collaborative process planning, modeling, control, prototyping, manufacturing, and engineering. Integration and interoperability in engineering. Typical areas can be building construction, aerospace, mechanical engineering, software engineering etc.

- Other cooperative applications that network, multiple units are involved such as cooperative learning, decision making, gaming, health caring, robotics.

- Basic theories, methods and technologies that support cooperation: big data, blockchain, Internet of Things (IOT), nano-networks, social media, crowd technology, knowledge management, ontology etc. applied to cooperative applications.

III. SUBMISSIONS

Manuscripts should be formatted according to the IEEE SMC Magazine guidelines for authors.

(<https://www.ieeesmc.org/publications/smc-magazine>), and submitted through the IEEE's Manuscript Central

(<https://mc.manuscriptcentral.com/smcmag>).

Please select "Special Issue" under Manuscript Category of your submission.

IV. IMPORTANT DATES

Manuscript submissions due: January 30, 2024

First round of reviews completed: March 15, 2024

Revised manuscripts due: April 20, 2024

Second round of reviews completed: May 30, 2024

Final manuscripts due: June 30, 2024

V. GUEST EDITORS

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